



*From Nano to Micro Power Electronics
And Packaging Workshop
November 30th, 2023
Tours, France
14th Edition*



TECHNICAL PROGRAM

Technical Committee:

Daniel ALQUIER	TOURS University	France	Co-chairman
Laurent BARREAU	ST Microelectronics Tours	France	Chairman
Lars BOETTCHER	FRAUNHOFER Institute	Germany	
Cyril BUTTAY	AMPERE Laboratory	France	
Jean-Luc DIOT	PRIVATE	France	
Franck DOSSEUL	MODULEUS	France	Co-chairman
Guo-Quan LU	VIRGINIA TECH	USA	
Stéphane BELLENGER	ST Microelectronics Grenoble	France	Co-chairman

8 h 20 Workshop package and badge distribution

8 h 50 Welcome and workshop program presentation

9 h 05 Keynote: DA5 consortium : approach towards Pb-free solutions in device packaging
Thomas Behrens & Andrei Damian – Infineon Technologies & NXP Semiconductors

9 h 55 Session 1: Designs, Applications & Reliability

9 h 55 3D power module through ceramic additive manufacturing – Emmanuel Marcault – CEA-Tech Occitanie, France

10 h 20 Coffee break / Table Top Exhibition and presentation

10 h 50 Session 1: Design, Applications & Reliability con't

10 h 50 Comprehensive approach for thin Cu ball bonding with reduced cratering – Indrajit Paul – ST Microelectronics Munich, Germany

11 h 15 Grid connected converter design for intelligent electricity storage in smart homes – Ismael Aouichak – GREMAN, University of Tours, France

11 h 40 Concepts for high-voltage power module by embedding SiC or GaN semiconductors – Lars Boettcher – IZM Berlin, Germany

12 h 05 Thermal enhancement solutions for smart power stage QFN packages in high-performance computing for AI and machine learning processors – Alastair Attard – UTAC Thailand

12 h 30 Table Top Exhibition visit and Lunch (Buffet)

13 h 40 Roundtable : Power Semiconductors : how to consolidate Europe as a 'powerhouse'?
Power devices and packaging in the context of the EU Chips Act
Moderator : Jean-Marc Yannou (ASE)
Speakers : experts from European companies and Universities

14 h 45 Session 2 : Materials, Processes and Technologies

14 h 45 Understanding the influence of copper substrate oxidation on silver pressure sintering performance – Thorsten Vehoff - Heraeus, Germany

15 h 10 Coffee break / Table Top Exhibition

15 h 40 Session 2: Materials, Processes and Technologies con't

15 h 40 Plasma dicing of GaN on Si wafers - James Weber - Panasonic Europe, Germany

16 h 05 Reliable assembly for high current / high voltage interconnexion – Christian Bremont – Renault, France

16 h 30 The latest material technology for power module packaging – Tan Tat Hong - Sumitomo Bakelite, Singapore

16 h 55 Processability and reliability of copper sintering for power electronics applications – Thorsten Vehoff – Heraeus, Germany

17 h 20 Closing

17 h 30 End of session

Next to the workshop sessions of Thursday, November 30th, a social event will be organized to close the workshop day for which you need to register if you wish to attend:

- ***a visit of a wine cellar in Loire Valley. Departure from Greman's institute at 17h45***
- ***a dinner in a gastronomic restaurant in Tours at 20h15***



Sponsors:

From Nano to Macro Power Electronics and Packaging European Workshop

Thursday, November 30th, 2023

GREMAN (ECOLE D'INGENIEURS POLYTECH TOURS)
Amphithéâtre du département électronique et énergie 7 avenue Marcel Dassault Tours

Registration Form Final registration Thursday November 30^h 2023

COMPANY:

NAME:

FIRSTNAME:

ADDRESS:

TEL:

E-MAIL:

→Send back to IMAPS France by E-mail: imaps.france@orange.fr

FEES (including conferences attendance, table top visit, lunch, coffee breaks, social event and closing dinner)

Conferences on free access on website www.imapsfrance.org after the event.

- IMAPS MEMBER 220 € HT excluding - 264 € TTC
- Non IMAPS MEMBER 250 € HT – 300.00 € TTC
- SPEAKERS/CHAIRS 180 € HT - 216 € TTC
- Table Top 300 € HT – 360.00 € TTC (1 table, chairs, display panel, conferences attendance, Coffee breaks, lunch, social event and closing dinner).

For foreign companies, VAT is excluded

Do not forget to tick boxes if you want to participate to our social event

- Visit of a Touraine specific place (Thursday evening) yes no
- Dinner after the visit (Thursday evening) yes no

- On line Payment and Registration available on www.france.imapseurope.org

PAYMENT BANK REFERENCES

Credit card accepted, as well as payment by cheque, cash or wire transfer.
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International Microelectronics Assembly & Packaging Society – France
17 rue de l'Amiral Hamelin 75016 Paris

How to reach GREMAN



Access by car from the A10 motorway

In the Paris-Bordeaux direction,

Take the exit n ° 22 Saint-Avertin, then follow the direction of the 2 Lions.

In the Bordeaux-Paris direction,

Take the exit n ° 23, follow the direction Tours-Center then the 2 Lions direction

Access by train and tram or bus

You can either go to the Tours train station which is in the city center or to the Saint Pierre des Corps railway station which is on the outskirts and which has both rail shuttles to Tours and buses to different points of the city. More info on the website of Fil Bleu.

Access to Polytech Tours by tram stop "Fac 2 Lions" or by bus by line 5 stop "Polytech".